MEI Form -1.2 (July 1, 2005)

Docket No.

DECLARATION A	ND P	OWER OF	ATTO	RNEY FO	R U.S. P/	atent ap	PLICATION
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I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment(s) referred to above.

I acknowledge my duty to disclose to the U.S. Patent and Trademark Office all information known to me to be material to patentability as defined in Title 37, Code of Federal Regulations, \$1.58.

I hereby claim foreign priority benefits under This 35, United States Code, §119 (a-d), §172, or §385(b) of any foreign application(s) for patent or inventor's certificate, or §385(a) of any PCT international application which designated at least one country other than the United States of America, listed below, and have also identified below any foreign application for patent or inventor's certificate, or of any PCT international application having a filing data before that of the application on which priority is claimed:

COUNTRY	APPLICATION NO.	DATE OF FILING	PRIORITY CLAIMED
US	60/569,537	May 10, 2004	Yes
us	60/577,616	June 7, 2004	Yes
US	60/605,488	August 31, 2004	Yes
บร	60/668,237	April 4, 2005	Yes

[☐] Additional foreign or international application numbers are listed on a supplemental priority sheet attached hereto.

I hereby claim the benefit under Title 35. United States Code \$119(e) of any United States Provisional application(s) listed below.

Number	(Day/Month/Year Filed)		
	,		

a Additional U.S provisional application numbers are listed on a supplemental priority sheet attached hereto.

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I hereby claim the benefit under Title 35, United States Code §120 of any United States application(s), or §365(C) of any PCT international application designating the United States of America, listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States or PCT international application in the manner provided by the first paragraph of Title 35, United States Code §112, I acknowledge the duty to disclose information material to patentability as defined in Title 37, Code of Federal Regulations, §1.58 which occurred between the filing date of the prior application and the national or PCT international filing date of this application.

Application no.	u.s. filing date	Status: Patenied, Pending, Abandoned
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a Additional U.S. or international application numbers are listed on a supplemental priority sheet attached hereto

POWER OF ATTORNEY: As a named inventor, I hereby appoint the attorneys and agents associated with U.S. Patent and Trademark Office Customer Number Identified beliew to prosecute this application and to transact all business in the U.S. Patent and Trademark Office connected therewith, and direct that all correspondence be addressed to that customer number.

I hereby authorize the U.S. attorneys and agents associated with the customer number to accept and follow instructions from Matsushita Electric industrial Co., Ltd., and any affiliated or subsidiary company thereof, received via their corporate representatives and/or their foreign patent attorneys or agents, if any, as to any action to be taken in the U.S. Patent and Trademark Office regarding this application without direct communication between the U.S. attorneys or agents and myself.

Direct Correspondence t	:	
	CUSTOMER NUMBER : 51921	
		;
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I further declare that all statements made herein of my own knowledge are true, and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code, and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

Full Name of Sole or First inventor	First Name Rajaev	Y.	LAST NAME Nagar	SIGNATURE	· .	F SIGNATURE
Residence & Citizenship	CITY Sammamish		STATE OR COU	NTRY	COUNTRY OF	CITIZENSHIP
Post Office Address	ADDRESS 1901 205th Plac		CITY Sammamish, WA	STATA, United States	E OR COUNTRY	21P CO5B 98074

Full Name of Second Inventor	FIRST NAME Garret	J.	LAST NAME Buban	SIGNATURE	DATE OF SIGNATURE
Realdence & Citizenahip	City Carnation		STATE OR COU WA	NTRY	COUNTRY OF CITIZENSHIP United States
Post Office Address	ADDRESS 9309 Tolt Highi	anda Rd	CITY NE, Carnation, W	STATE OF A, United States	COUNTRY ZIP CODE 98014

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Full Name of	FIRST NAME		LASTNAME	SIGNATURE	DATE	SIGNATURE
Third inventor	Yoshiho		GOTOH			- 1 - 1 - 1 - 1 - 1 - 1
				yoshiho goto	a Doc. 2	17, 2006
Residence & Citizenship	CITY		STATE OF COUN	TRY	COUNTRY OF	CHIZENSHIP
D=-1.04(=- 4.11-	Osaka		Japan		Japan	
Post Office Address	ADDRESS c/o Mataushita E	Electrio Ir	CITY dustrial Co., Ltd., 1008	atatg: Oaza Kadoma, Kadoma،	OR COUNTRY	ZIP CODE
				Table Tabl	om, Otaka (1 1-00)	or oapan
Full Name of	FIRST NAME		LAST NAME	SIGNATURE	57523	SIGNATURE
Fourth Inventor	Sarosh	C.	Havewala	O'GHAT ONE		
				2016en	11-1	-06
Residence & Citizenship	CITY		STATE OF COUN	TRY -	COUNTRY OF	CITIZENSHIP
	Redmond		WA	····	India	
Post Office Address	ADDRESS	40. 4-	CITY	STATE	OR COUNTRY	ZIP CODE
	16538 NE 337	J Ct, Ap	N. VV202, Redmon	d, WA, United States		98052
P(1 A)		***		•		
Full Name of Fifth Inventor	FIRST NAME	_	LAST NAME	SIGNATURE	DATE OF	SIGNATURE
- mm inventor	Revinder	8.	Thind	The same	y +11	1/06
Residence & Chizenship	CITY		STATE OR COUNT	RY	COUNTRY OF	
<u> </u>	Kirkland		WA	_	india	OHITCHOULP
Post Office Address	ADDRESS		CITY	STATE	OH COUNTRY	ZIP CODE
	13235 120th A	ve NE, I	Arkland, WA, United	States		98034
- 44						
Full Name of Soxth Inventor	FIRST NAME Vishal	.,	LAST NAME	BIONATURE	DATEOF	SIGNATURE
	Visnat	V.	Ghotge	العرابط	111	106
Residence & Citizenahip	CITY	~~~~	STATE OF COUNT	- W	COUNTRY OF	. –
	Seattle		Washington		india	CHIZENSHIP
Poet Office Address	ADDRESS		CITY	STATE C	R COUNTRY	ZIP CODE
	424 Summit Av	e East,	#301, Seattle, WA,	United States		98102